

IN THE SPECIFICATION

Page 1, in the heading, please cancel "tesa...Description".

Page 1, before the first line of text, please insert:

--This is a 371 of PCT/EP2004/053632 filed 21 December 2004 (international filing date).--

Page 1, line 14, please insert:

--Background of the invention--

Page 3, line 3, please insert:

--Summary of the invention--

Page 3, line 15, please insert:

--Brief description of the drawings

The drawing illustrates the adhesive bonding of an electrical module to a card body to produce a chip card.

Detailed description--

Paragraph beginning on page 5, line 13 (amended)

The adhesive bonding of the electrical module 2 to a card body 3 to produce what is shown as a chip card is depicted diagrammatically in **Fig. 1 the drawing**. The inventive temperature-activable adhesive 1 possesses a layer thickness of between 10 and 100

μm in one preferred version and a layer thickness of 30 to 80 μm in a particularly preferred version.